

Title (en)

METHOD AND APPARATUS FOR LASER CUTTING MATERIALS

Title (de)

VERFAHREN UND VORRICHTUNG ZUM LASERSCHNEIDEN VON WERKSTOFFEN

Title (fr)

PROCEDE ET APPAREIL DE DECOUPAGE D'OBJETS AU LASER

Publication

EP 0857098 A1 19980812 (EN)

Application

EP 96937024 A 19961025

Priority

US 9617226 W 19961025

Abstract (en)

[origin: WO9715417A1] An improved method and apparatus of cutting an object with a laser beam, comprising using a diode laser-pumped pulsed solid state laser having an average power output from about 2 to about 100 watts and delivering an average laser beam brightness of greater than 10^{12} W/m²*sr and a peak brightness of greater than 10^{13} W/m²*sr to the object. Objects cut with the laser cutting method having heat affected zones (HAZ) of less than 4 mm, and having substantially no microcracks.

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CPC (source: EP)

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